



SOT849-1

plastic quadruple in-line package; 90 leads

8 February 2016

Package information

1. Package summary

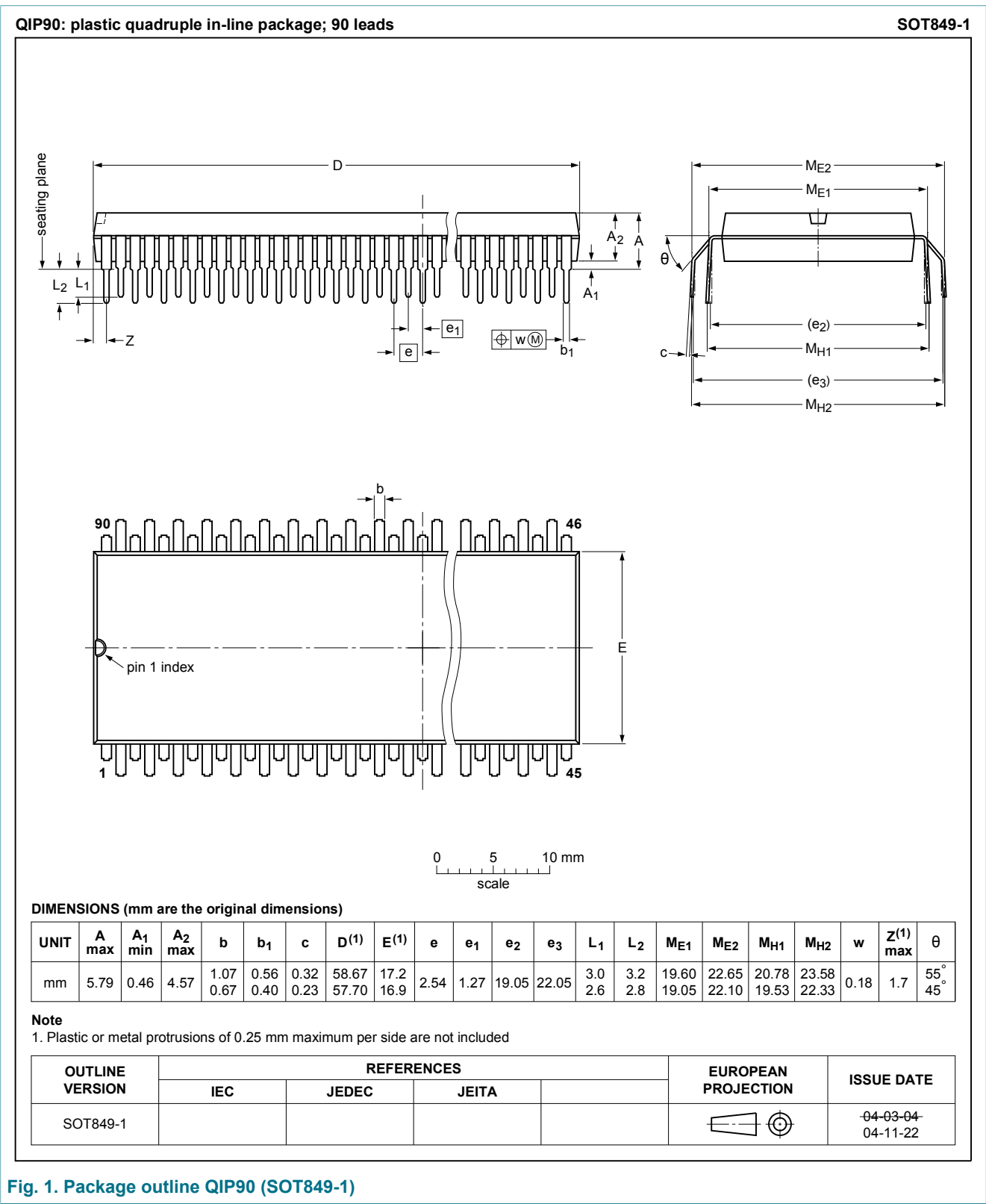
Terminal position code	D (double)
Package type descriptive code	QIP90
Package type industry code	QIP90
Package style descriptive code	QIP (quadruple in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	22-11-2004

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		57.7	-	58.16	58.67	mm
E	package width		16.9	-	17	17.2	mm
A	seated height		[tbd]	-	5.79	5.79	mm
A ₂	package height		[tbd]	-	4.25	4.57	mm
n ₂	actual quantity of termination		-	-	90	-	



2. Package outline



3. Legal information

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